

Polyimides

Stress Buffer, RDL and ILD Materials

Photosensitive Materials

BENEFITS

- Lower Cost of Ownership
- Fewer Processing Steps
- Aqueous and Solvent Develop
- Positive-tone and Negative-tone
- Superior Mechanical Properties
- Excellent Electrical Properties
- Internal Adhesion Promoters
- Thick Film Processing

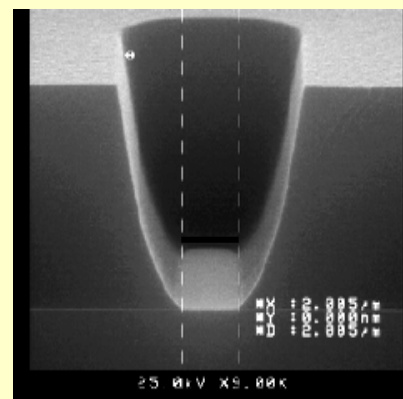
AQUEOUS DEVELOPABLE

- AP2210B Positive-tone
- AN3310 Negative-tone

SOLVENT DEVELOPABLE

- Durimide® 7500 Series
- Durimide® 7300 Series
- Durimide® 7000 Series

2 μ m fuse window



CD 2.01 μ m

Non-Photosensitive Materials and Ancillaries

NON-PHOTOSENSITIVE

- Durimide® 200 Series
Pre-imidized Polyimide
- Durimide® 10/32 Series
Pre-imidized Polyimide-amide
- Durimide® 100 Series
Polyamic Acid
- LTP-18A Polyamic Acid
Low Temperature Cure

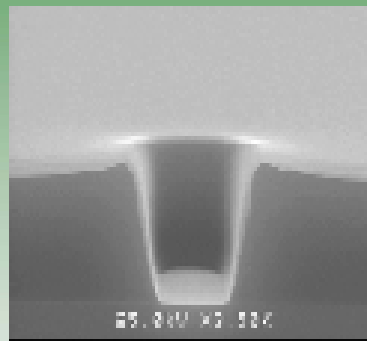
ANCILLARIES

- QZ3501
Developer
- HTRD-2
Developer
- QZ3701
Edge-bead Remover
- QZ3322
Polyimide Stripper

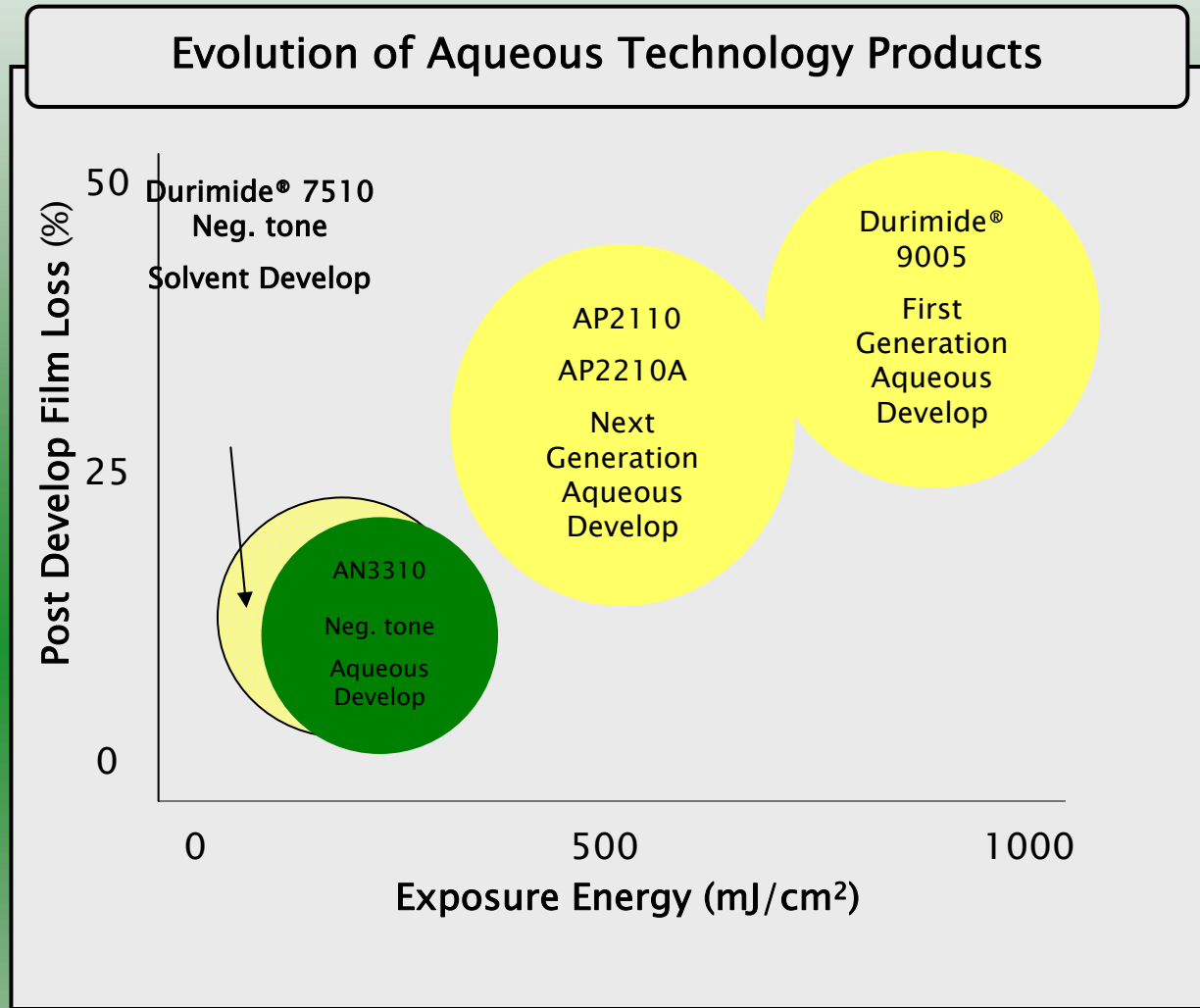
AN3310 Negative-tone Stress Buffer, RDL and ILD Coating

Features/Benefits

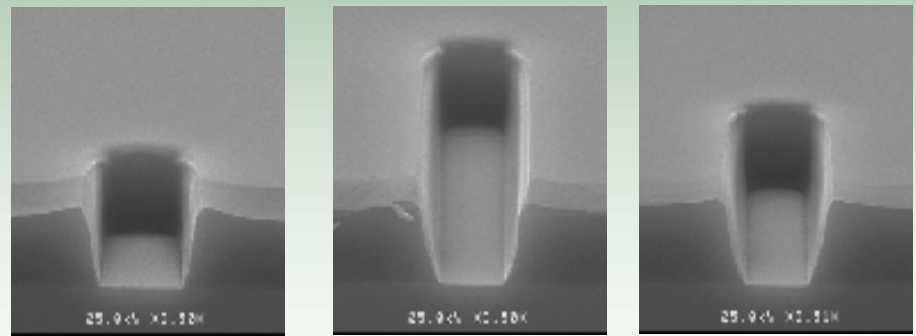
- Single Mask Process
- TMAH Developable
- Non-NMP Formulations
- Positive and Negative-tone
- Internal Adhesion Promoter
- Superior Mechanical Properties
- Positive and Negative-tone



5 μm via in a 7 μm cured film



AN3310 Exposure Latitude – 7 μm fuse trench in 7 μm cured film



110mJ/cm 210mJ/cm² 310mJ/cm²

AN3310

Cure Process

